alpha



ALPHA Solder Preforms for PCB Assembly

Solutions for Challenging PCB Assembly Applications



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ASSEMBLY SOLUTIONS

ALPHA Solder Preforms for PCB Assembly

For over 50 years, Alpha's Solder Preforms have provided versatile, custom solutions for a variety of SMT challenges in PCB Assembly. By providing a repeatable and precise volume of solder, the technology improves the reliability and performance of components used in SMT assembly.

ALPHA Exactalloy[®] solder preforms are the enabling technology that have set the surface mount industry standard for product innovation and utility. Alpha was the first to

introduce solder preforms in tape and reel packaging and provided the innovation that set the industry standard for developing the world's smallest volume solder preforms – first with the introduction of the 0402 preform and then with the 0201 preform.

Alpha's latest preform innovations include void reduction solutions, bond line control mechanisms, along with NEW high reliability and low temperature alloys. Our solutions are based on dedicated research and development work which is focused on meeting your PCB Assembly requirements.



ALPHA Preform Technologies for PCB Assembly provide solutions for:

Increase Solder Volume

- Selective
 solder volume
 increase
- Solder joint strengthening
- Reduction of flux residues
- Supports intrusive reflow
- Elimination of step stencils
- Low temperature compatible

Paste free Soldering

- Features integrated flux, for pastefree soldering
- Provides 100% hole fill reliability
- Supports Eliminationof-Wave Soldering
- Low temperature compatible

Void Reduction

- AccuFlux[®] technology enables consistent void levels to < 10%
- Eliminates
 rework due
 to excessive
 voids
- Available for many standard bottom terminated component package sizes

Spacer Technology

- Sets a fixed bond line thickness
- Stops corner solder bridging in high density BGA devices
- Prevents
 component tilt
- Provides a path for void evacuation under components

INCREASE SOLDER VOLUME

With electrical components sizes becoming ever smaller, printing sufficient amounts of solder paste onto miniaturized, overpopulated PCBs has become increasingly challenging. **ALPHA Exactalloy Tape and Reel Preforms** are specifically designed to overcome these solder volume deficiencies, enhancing the solder joint strength and reliability and providing 100% hole fill.

ALPHA Exactalloy Preforms in tape and reel packaging provide an easy to implement method for increasing the solder volume of SMT and through-hole components assembled using surface mount technology. Specifically targeted for use with solder paste in SMT assembly applications, small solder rectangles are inserted into solder paste to precisely increase solder volume, the solder paste acting as both an adhesive and flux vehicle. The solder rectangles are 100% alloy, and due to the minimal amount of solder paste required to provide adequate wetting, near zero flux residue is realized.

The entire family of solder rectangles in tape and reel packaging are placed with standard pick and place equipment, utilizing industry standard chip capacitor size preforms for ease of use.





A preform added to solder paste yields 100% hole fill plus fillet.

Restricted Printing Area



Solder paste as printed



Preforms placed in paste



Solder paste and preforms reflowed



Add a preform to an SMT component lead to increase joint strength.



Visit MacDermid Alpha's YouTube channel for preform technology videos.



ALPHA Exactalloy Tape and Reel Preforms enable the use of standard pick and place equipment.



Preforms provide additional solder for tight pitch components and thick PCBs ensuring 100% hole fill and fillet formation.

INCREASE SOLDER VOLUME

Alpha Exactalloy Tape and Reel Preforms provide customers with:

- Increased solder joint reliability
- Improved first pass yields
- 100% hole fill
- Increased solder volume without the need for PCB layout changes or use of step stencils
- A significant time-to-market advantage with the use of tape and reel packaging

ALPHA Exactalloy Preforms are available in a wide variety of solder alloys, including low temperature, RoHS compliant alloys, such as SnBiAg and the Innolot alloy for extra joint strength.



Different chip cap. size solder preforms applied before reflow

Desired result after reflow, the 0603 chip cap. size creating the largest fillet

Size		Dimensions			Volume	Dimensions			\/_l	e O	م	m e
		а	b	с	voiume	a	b	c	volume	Ъ-Ч-	I-P	v Te∣ b-fr∈
inch	mm	mm		mm³	mil			mm²	Ы	N N	Γο	
0201	0503	0.47	0.28	0.28	0.037	19	11	11	2,249			
0202	0505	0.51	0.51	0.25	0.065	20	20	10	3,968	/		
030155	06035	0.60	0.35	0.35	0.074	24	14	14	4,485			
0402H	1006H	1.00	0.60	0.25	0.150	39	24	10	9,154	~		
0402	1005	1.00	0.50	0.50	0.250	39	20	20	15,256	~		
0402B	10055	1.00	0.55	0.55	0.303	39	22	22	18,460	~	*	*
0603H	1608H	1.60	0.80	0.50	0.640	63	31	20	39,055	~		
0603	1608	1.60	0.80	0.80	1.024	63	31	31	62,488	~		
0805H	2013H	2.01	1.30	0.40	1.045	79	51	16	63,782	~		
0805	2013	2.01	1.30	0.76	1.986	79	51	30	121,186	~		
0805S	20135	2.01	1.30	1.30	3.397	79	51	51	207,292	~		*
1406	3515	3.56	1.52	0.77	4.167	140	60	30	254,263	~		*

* Production will depend on market demand. Please check with your local sales representative for availability.



PASTE FREE SOLDERING USING SOLDER WASHERS

Achieving 100% hole fill on throughhole components can be problematic. **ALPHA Exactalloy Solder Washers** provide a precise amount of solder volume to allow for a highly repeatable soldering process, in many cases, ensuring a top and bottom fillet for extra joint strength.

Alpha's Solder Washers are supplied with integrated flux eliminating the need for solder paste. The solder washer is placed directly over the component's through hole pin and provides adequate solder and flux to fill the plated through hole. ALPHA Exactalloy Solder Washers enable customers with:

- Increased hole fill to 100%
- Elimination of wave and secondary manual soldering processes
- Low temperature soldering processes with temperature sensitive through hole components
- Supports non-traditional PCB soldering methods such as induction, laser resistance and vapor phase soldering

ALPHA Exactalloy Solder Washers are available in a wide range of custom sizes, as well as an assortment of rosin based and water soluble fluxes to meet your assembly needs. These preform washers support all Alpha alloys enabling low temperature soldering processes for through-hole components that cannot tolerate standard SMT reflow temperatures. ALPHA Exactalloy Solder Washers can be supplied in bulk or tape and reel packaging for automated assembly.



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0	id	od

Min = 0.76mm (.030") Max = 47.63mm (1.875")

id

od

Min = 0.25mm (.010") Max = 34.93mm (1.375")

t (thickness)

Min = 0.10mm (.004") Max = 2.80mm (.110")

Alpha has close to 1,000 washer sizes and countless thicknesses available to meet your specific assembly requirements.

ALPHA external flux coating for preforms	Flux classification		Remarks					
Flux name	QQS 571	J-STD						
RS2	RMA	ROLO	No clean, halide free, mildly activated flux (Finishes: Ni/Au, Ag, Cu, etc.)					
RS2.2	RMA	R0L1	No clean, mildly activated flux (Finishes: Ni/Au, Ag, Cu, etc.)					
RS4	RA	R0M1	No clean flux with higher activation (Finishes: Brass, NiAg, Cu, Sn, etc.)					
RS7	RSA R0H1		No clean flux with highest activation for challenging soldering surface					
ALPHA internal flux core for preforms	Flux classification		Remarks					
Flux name	QQS 571	J-STD						
HF-850	RMA	ROLO	Halogen-free, mildly activated flux (Finishes: Ni/Au, Ag, Cu, etc.)					
SMT	RA	R0M0	Halide-free flux with higher activation (Finishes: Brass, Ni, Cu, Sn, etc.)					
Fluitin 1532	RA	R0M1	R0M1 type flux for use in Europe only.					
RS7MI	RSA R0M1		Highest flux activation for challenging soldering surfaces.					
ALPHA external flux core for preforms	Flux classification		Remarks					
Flux name	QQS 571	J-STD						
BTC-578	RMA ROLO		Zero-halogen , mildly activated flux (Finishes: Ni/Au, Ag, Cu, etc.)					

VOID REDUCTION SOLUTIONS

The increased use of bottom terminated component packages (e.g., QFN, QFP, and DPAK), has posed the assembly industry with significant challenges in void reduction due to higher power densities, increased thermal reliability and peak RF performance requirements. **ALPHA AccuFlux BTC-578 Preforms** are specifically designed to provide the industry's lowest and most consistent void reduction performance for bottom terminated component assemblies.

ALPHA AccuFlux BTC-578 Preforms are designed to enhance reliability and heat transfer through the reduction of voids at

the thermal interface assembly level of bottom terminated components. The AccuFlux BTC-578 technology employs a combination of low void flux with a precision controlled micro-flux coating process. Alpha's proprietary flux application process ensures a consistent coating from preform to preform and lot to lot, which is paramount to enabling repeatable, low void performance.

ALPHA AccuFlux BTC-578 Preforms provide customers with:

- Effective heat dissipation through consistent low void level
- Enhanced process stability and predictable reliability through repeatable void distribution
- Maximizes mechanical strength through increased solder volume
- Enhanced electrochemical reliability from low flux residues

ALPHA AccuFlux BTC-578 Preforms are packaged in tape and reel to provide an easily implemented void reduction solution for new or existing PCB assemblies.



ALPHA AccuFlux BTC-578 Preforms are sized to support the most common bottom terminated component packages (QFN, QFP, D-PAK, etc.) to optimize void reduction.

	L	V	V	Standard Thickness (T)			
mm	inch	mm	inch	mm	inch	mm	inch
1.40	0.055	1.40	0.055	0.10	0.004	0.15	0.006
2.00	0.079	2.00	0.079	0.10	0.004	0.15	0.006
2.40	0.094	2.40	0.094	0.10	0.004	0.15	0.006
3.00	0.118	3.00	0.118	0.10	0.004	0.15	0.006
3.40	0.134	3.40	0.134	0.10	0.004	0.15	0.006
3.90	0.154	3.90	0.154	0.10	0.004	0.15	0.006
4.40	0.173	4.40	0.173	0.10	0.004	0.15	0.006
4.70	0.185	4.70	0.185	0.10	0.004	0.15	0.006
4.90	0.193	4.90	0.193	0.10	0.004	0.15	0.006

Production will depend on market demand. Please check with your local sales representative for availability.



Minimal voiding with BTC Preform



Void result using solder paste only



SPACER TECHNOLOGY

In modern electronic assembly applications, creating a very tightly controlled gap between the printed circuit board and electronic components can prove to be essential. ALPHA TrueHeight® Spacers were specifically designed to control corner solder bridging caused by BGA warp during reflow. Since then, other uses have been realized. Adding a precision standoff will prevent bond line thickness variations, component tilt, and excessive voids.

ALPHA TrueHeight Spacers are burr free, noncollapse, plated copper discs with superior height accuracy. TrueHeight Spacers are designed to be automatically placed and reflowed on a SMT pad using a small amount of solder paste. Where SMT pads cannot be found, component adhesive can be used for attach.

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Part Type Part Type inch mm inch inch mm mm DS-D076H010 DS-D030H004 0.76 0.030 0.10 0.004 b DS-D076H025 DS-B030H010 0.76 0.030 0.25 0.010 DS-D076H030 DS-D030H012 0.76 0.030 0.30 0.012 DS-D076H038 DS-D030H015 0.76 0.030 0.38 0.015

Contact your local sales representative for all available sales.

Control of Corner Solder Bridging





ALPHA TrueHeight Spacers provide

SPACER SOLDER PASTE PAD

 Precise height control for managing solder bond line thickness

customers with:

- A hard stop feature that manages component tilt and provides clearance for void escape
- A precision standoff to offset any throughhole component to allow intrusive reflow

ALPHA TrueHeight Spacers are available in a number of different heights, and are packaged in tape and reel for easy implementation into any pick and place operation.



ALPHA Solder Preforms for PCB Assembly



ALPHA Exactalloy solder preforms are available in a wide range of leaded and lead-free alloys to meet the most challenging assembly requirements.

Leaded Exactalloy	Melting Temp Range		Remarks		
Alloy Name	°C	°F			
Sn62 Pb36 Ag2	179	354	Silver containing eutectic alloy		
Sn63 Pb37	183	361	Most popular leaded eutectic alloy		
Sn60 Pb40	183-188	361-370	Off-eutectic, silver free alloy		
In50 Pb50	184-209	363-408	High ductility alloy		
Low Temp Leaded Exactalloy	Mel Temp	ting Range	Remarks		
Alloy Name	°C	°F			
Sn12.5 Pb25 Cd12.5 Bi50	69-71	156-160	Ultra low temperature, cadmium containing		
Sn16 Pb32 Bi52	95-96	203-205	Ultra low temperature, cadmium free		
Sn25 Pb25 Bi50	95-115	203-239	Low temperature, cadmium free		
High Temp Leaded Exactalloy	Melting Temp Range		Remarks		
Alloy Name	°C	°F			
Sn10 Pb88 Ag2	268-290	514-554			
Sn5 Pb92.5 Ag2.5	280	536			
Sn2 Pb95.5 Ag2.5	299-304	570-579	Most popular high leaded, high temperature		
In5 Pb92.5 Ag2.5	300	572	unoys		
Sn5 Pb95	310-314	590-597			

RoHS Compliant Exactalloy	Melting Temp Range		Remarks		
Alloy Name	°C °F				
SAC305*	217-221	422-430	Most popular RoHS compliant alloy		
SACX	217-228	422-442	Low silver (Ag0.3) SAC alloy		
Sn96.5 Ag3.5	221	430	Eutectic, copper free		
SN96 Ag4	221-238	430-460	Off-eutectic, copper free		
Sn99 Sb1	235	455	Eutectic, Sb containing alloy		
Sn95 Sb5	232-240	450-464	Off-eutectic, Sb containing alloy		
Low Temp RoHS	Melting				
Compliant Exactalloy	Temp Range		Remarks		
Alloy Name	°C	°F			
Sn42 Bi58	138	280	Eutectic, RoHS compliant alloy		
Sn42 Bi57.6 Ag0.4	138-139	280-282	Silver added for ductility		
Sn60 Bi39.6 Ag0.4	138-170	280-338	Off-eutectic, low temperature RoHS alloy		
Sn52 In48	118-131	244-268	Ultra low temperature, off eutectic alloy		
Sn48 In52	118	244	Ultra low temperature, eutectic alloy		
High Reliability RoHS Compliant Exactalloy	Melting Temp Range		Remarks		
Alloy Name	°C	°F			
Innolot	206-218	403-424	High reliability alloy		
Powerbond® 2050	235-240	455-464	Thermal fatigue resistance alloy		
Powerbond [®] 2110	222-266	432-511	Thermal fatigue resistant, high thermal conductive alloy		

*Various other SAC alloy variants can be made available, including SAC105, SAC387 and SAC405 **Above listed alloys are the most commonly used types in our industries. Please consult us about the availability of other alloys.

For available preform shapes, alloys, sizes and flux options, please refer to the corresponding Technical Bulletin or contact your local Alpha Sales Office.

Sustainability 🥖

All ALPHA Exactalloy Solder Preforms are produced in an ISO 14001 & 45001 qualified production environment. This certification ensures strict adherence to environmental management systems with a strong focus on health and safety. All metal waste resulting from our manufacturing processes is recycled.

ALPHA Exactalloy Solder Preforms are manufactured in TS16949 certified production sites.

During assembly processes, solder preforms support the use of alternative soldering methods like induction, laser or light beam soldering, using short bursts of energy rather than prolonged energy consumption associated with traditional soldering methods. ALPHA Exactalloy Solder Preforms are available in a range of low temperature, RoHS compliant alloys, enabling the most energy efficient soldering solutions.



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Alpha is a product brand of MacDermid Alpha Electronics Solutions.

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